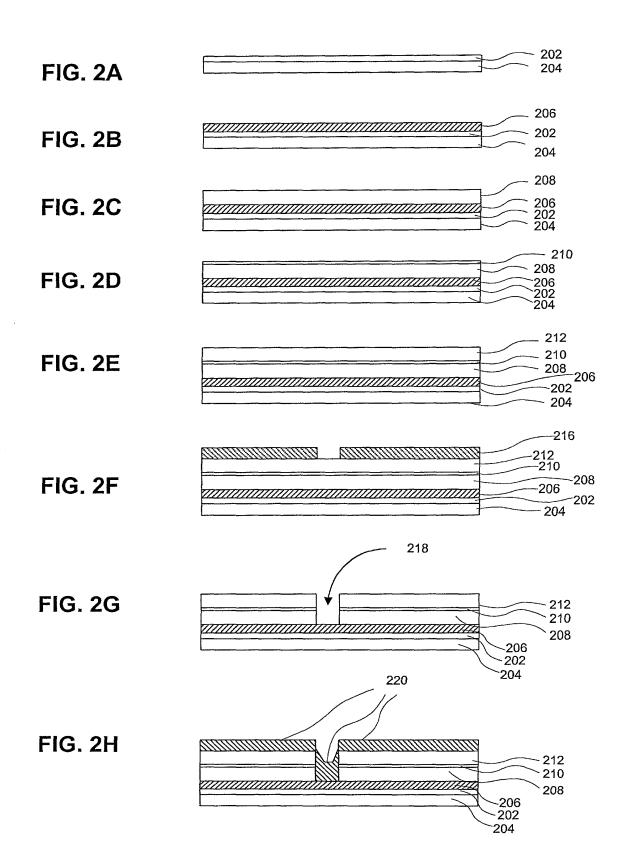


FIG. 1





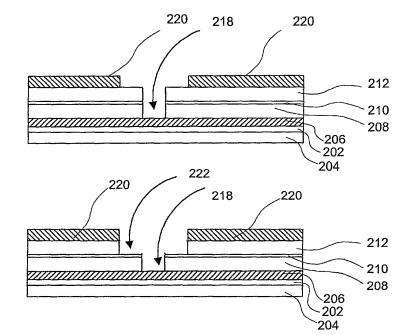


FIG. 2J

216' -216' FIG. 2F' -208 206 -202 - 204 216' .222 FIG. 2G' -216' -208 206 **-202** ~ 204 -220' -208 FIG. 2H' 206 -202 - 204

220a'

218

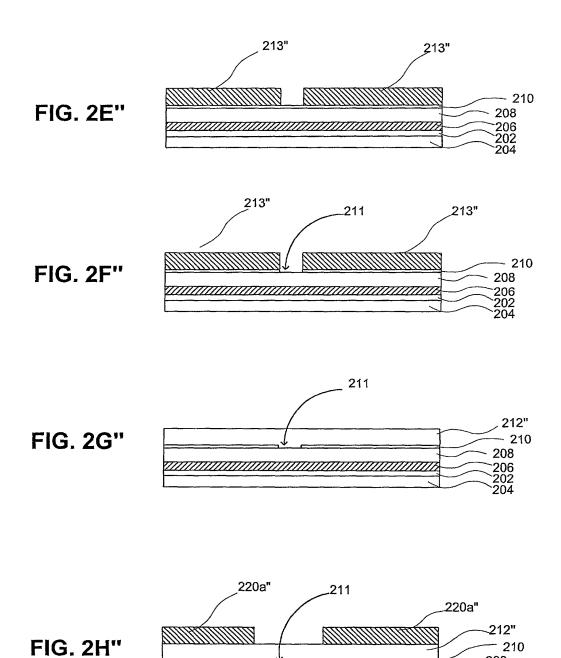
-220a'

-208

----202 -- 204

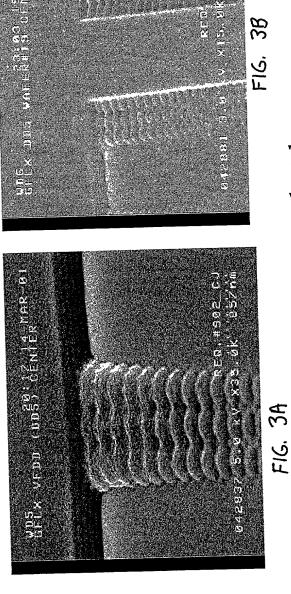
206

FIG. 21'



Resist poisoning using std. N incorporated SiC barrier film

After trench patterning

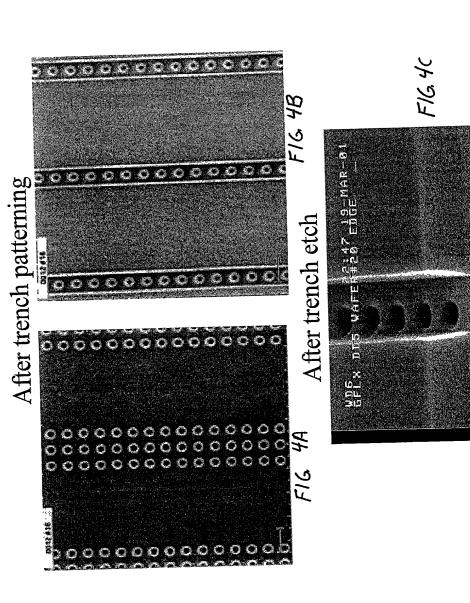


MDS DDS WAFER#20 DENTER

After trench etch



Resist poison was solved by using 2-layer barrier stack in which top layer is N



842881 3.0 KV X50.0K 6586mm